

# SOT627-1

plastic thin fine-pitch ball grid array package; 81 balls; body  
8 x 8 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA81
<b>Package type industry code</b>	TFBGA81
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-216
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	15-2-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A <sub>2</sub>	package height	0.75	-	0.8	0.85	mm
n <sub>2</sub>	actual quantity of termination	-	-	81	-	



2. Package outline

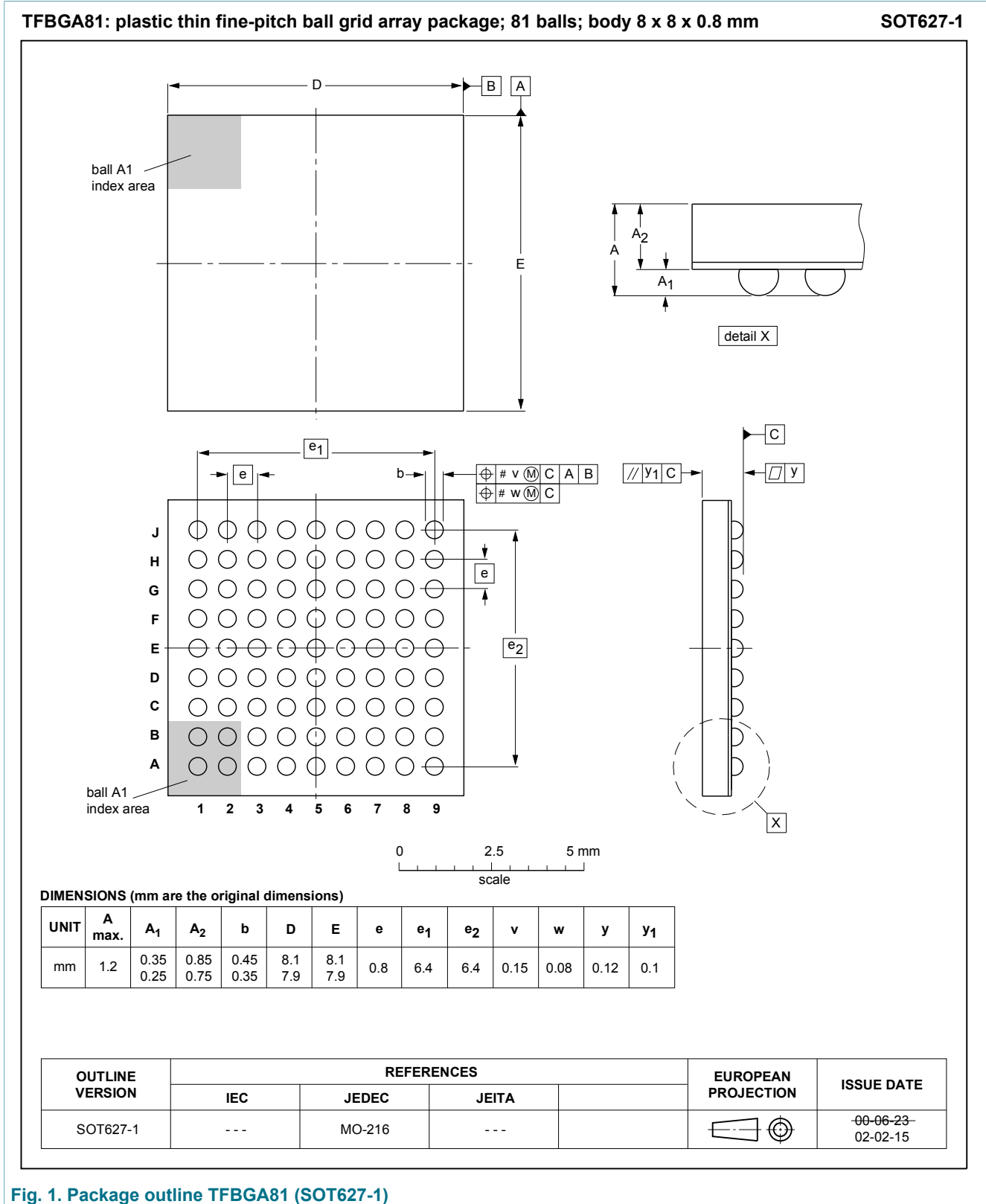


Fig. 1. Package outline TFBGA81 (SOT627-1)

### 3. Soldering

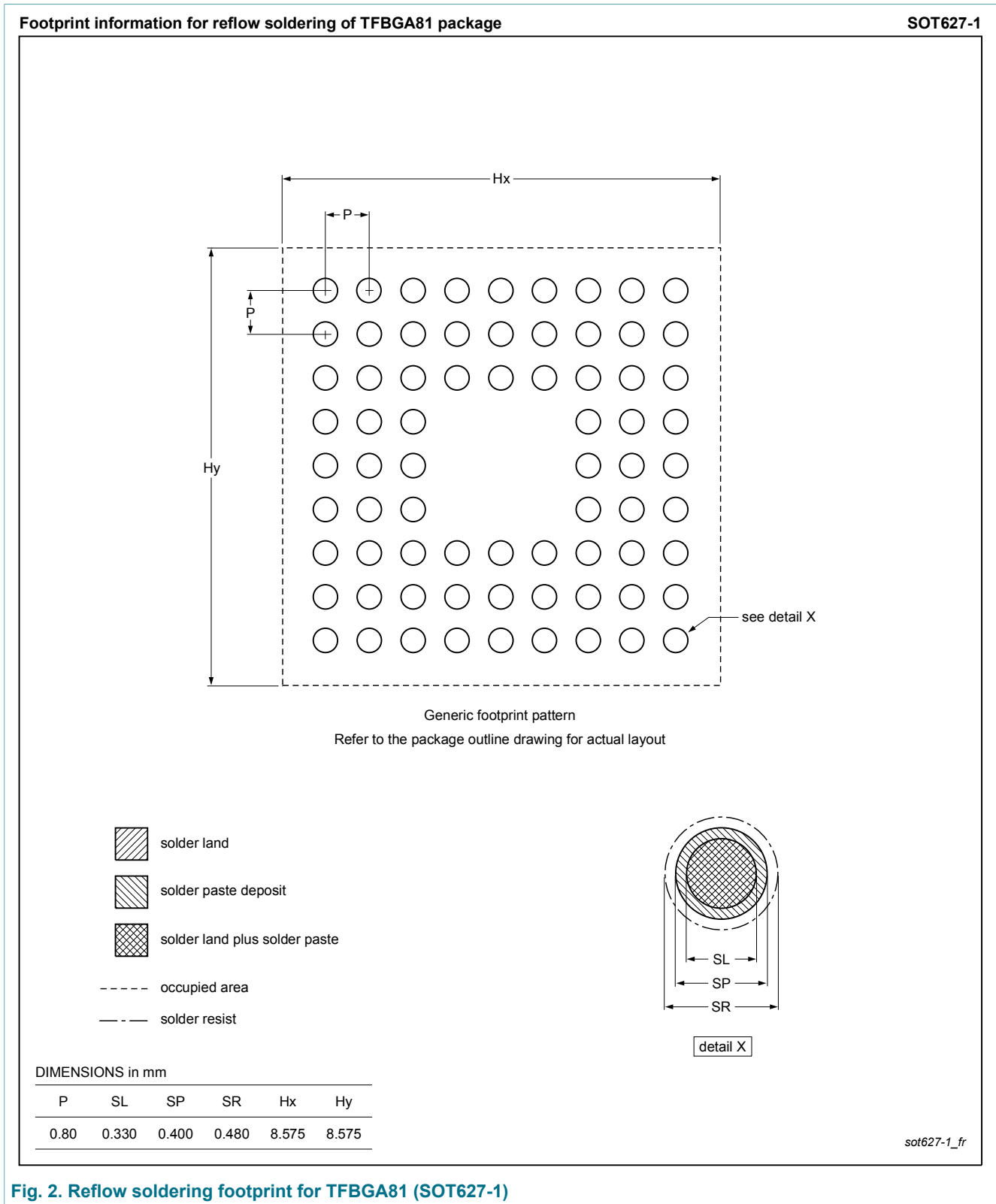


Fig. 2. Reflow soldering footprint for TFBGA81 (SOT627-1)

## 4. Legal information

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